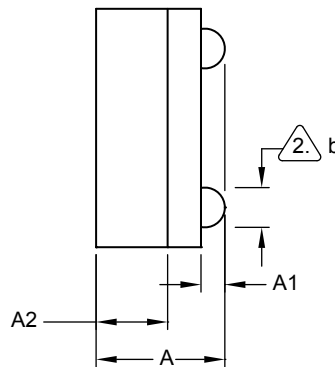
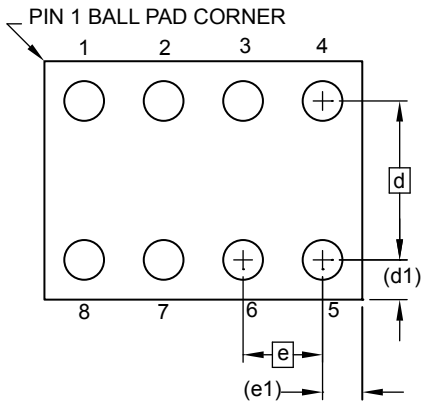


PIN 1 BALL PAD CORNER

TOP VIEW



SIDE VIEW



BOTTOM VIEW
8 SOLDER BALLS

COMMON DIMENSIONS
(Unit of Measure - mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.73	0.79	0.85	
A1	0.09	0.14	0.19	
A2	0.40	0.45	0.50	
b	0.20	0.25	0.30	2
D	1.50 BSC			
E	2.0 BSC			
e	0.50 BSC			
e1	0.25 REF			
d	1.00 BSC			
d1	0.25 REF			

Notes:

1. This drawing is for general information only.
2. Dimension 'b' is measured at maximum solder ball diameter.
3. Solder ball composition shall be 95.5Sn-4.0Ag-.5Cu.

6/11/13

TITLE
8U3-1, 8-ball, 1.50mm x 2.00mm body, 0.50mm pitch,
Very Thin, Fine-Pitch Ball Grid Array Package (VFBGA)

GPC
GXU

DRAWING NO.
8U3-1

REV.
F